

# **HRW0203A**

# Silicon Schottky Barrier Diode for Rectifying

REJ03G0154-0400Z

(Previous: ADE-208-014C)

Rev.4.00 Jan.06.2004

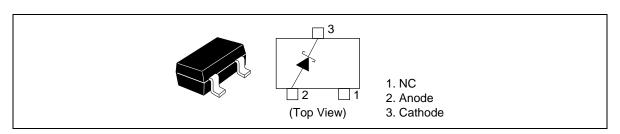
#### **Features**

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK package is suitable for high density surface mounting and high speed assembly.

#### **Ordering Information**

Type No.	Laser Mark	Package Code	
HRW0203A	S5	MPAK	

#### **Pin Arrangement**



## **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V <sub>RRM</sub> *1	30	V	
Average rectified current	l <sub>O</sub> * <sup>1</sup>	200	mA	
Non-Repetitive peak forward surge current	I <sub>FSM</sub> *2	2	А	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Notes: 1. See from Fig.1 to Fig.5, with polyimide board.

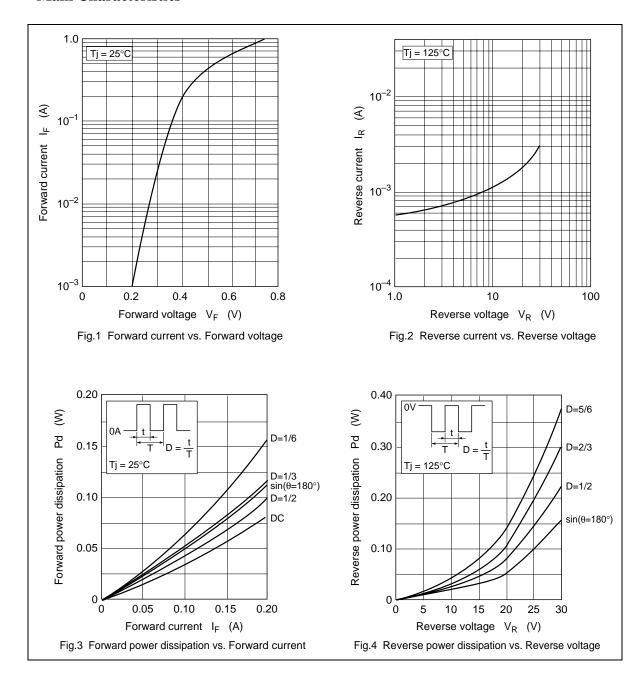
2. 50 Hz sine wave 1 pulse.

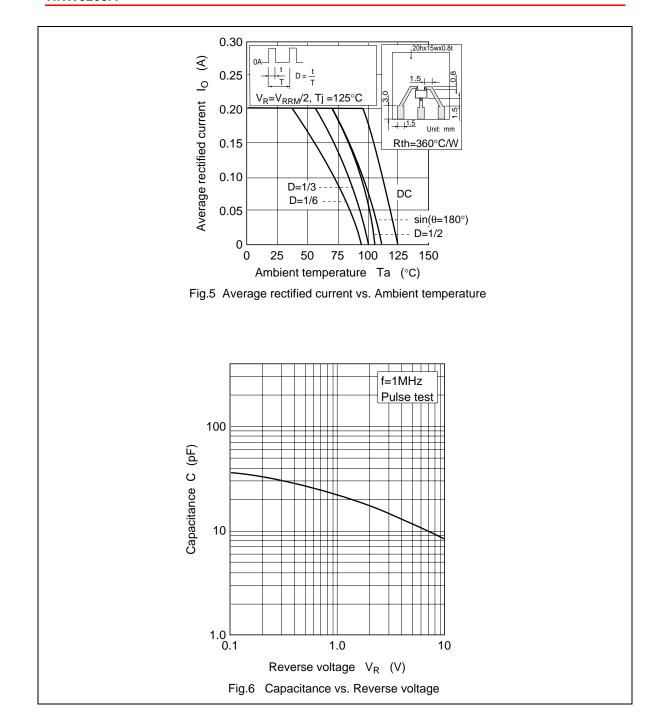
#### **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

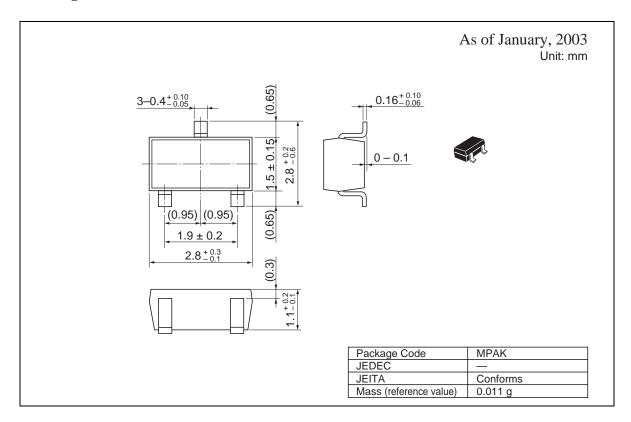
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V <sub>F</sub>	_	_	0.5	V	I <sub>F</sub> = 200 mA
Reverse current	I <sub>R</sub>	_	_	50	μΑ	V <sub>R</sub> = 30 V
Capacitance	С	_	40	_	pF	$V_R = 0 V, f = 1 MHz$

#### **Main Characteristics**





## **Package Dimensions**



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